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(12) **United States Design Patent**
Shimamoto et al.

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(45) **Date of Patent:** **** Jun. 16, 2015**

(54) **HEAT MEDIUM RELAY UNIT**

2229/02; H01H 2229/036; H01H 13/04;
H01H 13/48; H01H 1/58; H01T 13/34;
H02H 9/02

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See application file for complete search history.

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(56)

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(**) Term: **14 Years**

(21) Appl. No.: **29/469,912**

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Related U.S. Application Data

(62) Division of application No. 29/426,046, filed on Jun.
29, 2012, now Pat. No. Des. 700,896.

(57)

CLAIM

The ornamental design for a heat medium relay unit, as shown
and described.

(30) **Foreign Application Priority Data**

Jan. 27, 2012 (JP) 2012-001561

Jan. 27, 2012 (JP) 2012-001562

DESCRIPTION

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/159**

(58) **Field of Classification Search**
USPC D13/110, 123, 146, 147, 151, 153, 154,
D13/158–164, 171, 174, 184, 199;
D14/240, 356–358, 434; 200/43.14,
200/50.01, 50.21–50.23; 361/42, 44, 50,
361/71, 115, 608, 622, 627, 628, 634, 690;
439/532, 536, 540.1, 541.5, 613, 614,
439/884, 894, 895
CPC H01H 13/705; H01H 13/88; H01H
2011/0087; H01H 2205/016; H01H 2221/05;
H01H 2227/016; H01H 2227/026; H01H

FIG. 1 is a front, top and right side perspective view of a heat
medium relay unit, showing an embodiment of our new
design;

FIG. 2 is a rear, top and left side perspective view thereof;

FIG. 3 is a front elevation view thereof;

FIG. 4 is a rear elevation view thereof;

FIG. 5 is a left side elevation view thereof;

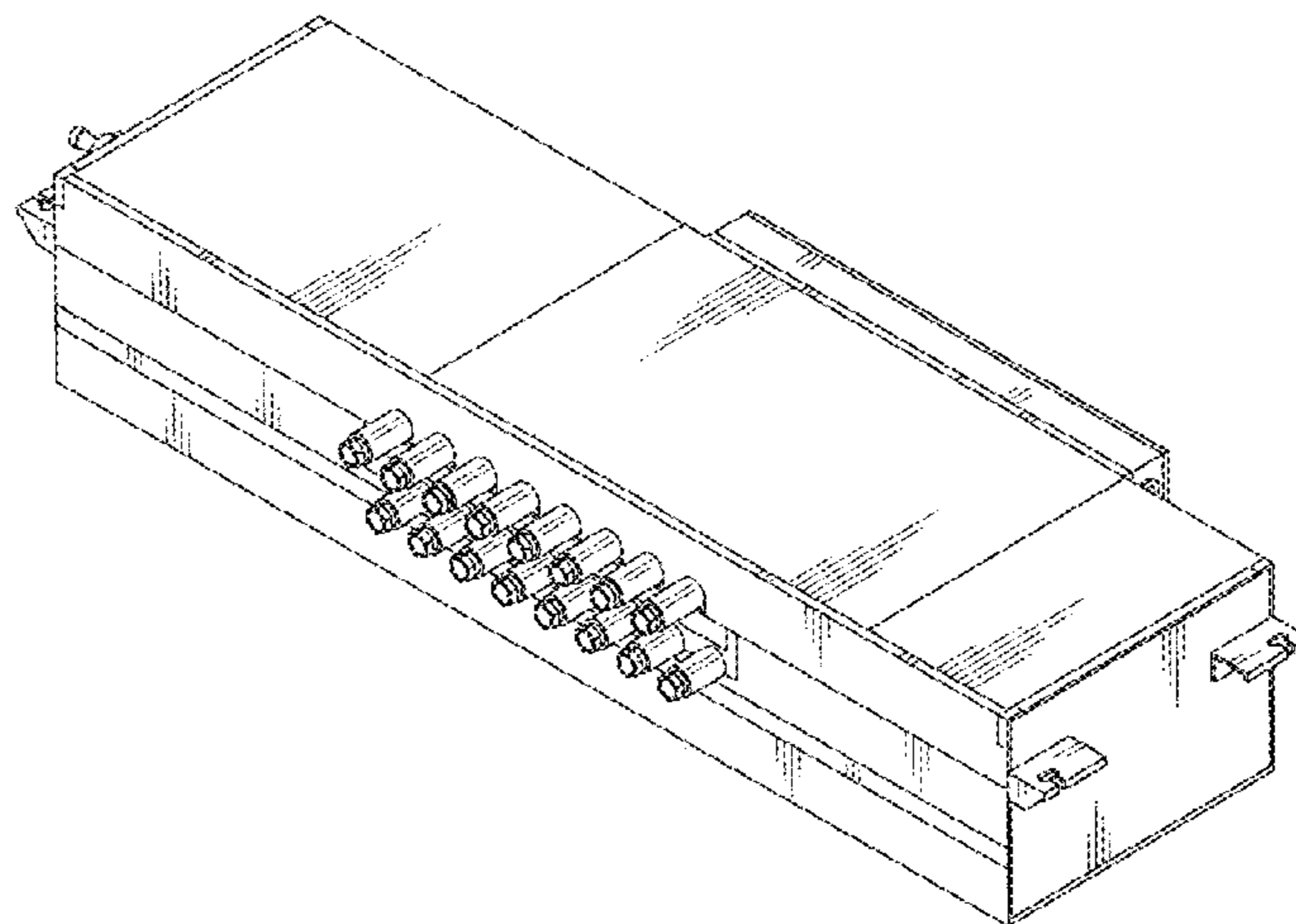
FIG. 6 is a right side elevation view thereof;

FIG. 7 is a top plan view thereof; and,

FIG. 8 is a bottom plan view thereof.

The broken line portion of the figure drawings is included to
show unclaimed subject matter only and forms no part of the
claimed design.

1 Claim, 6 Drawing Sheets



(56)

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Fig. 1

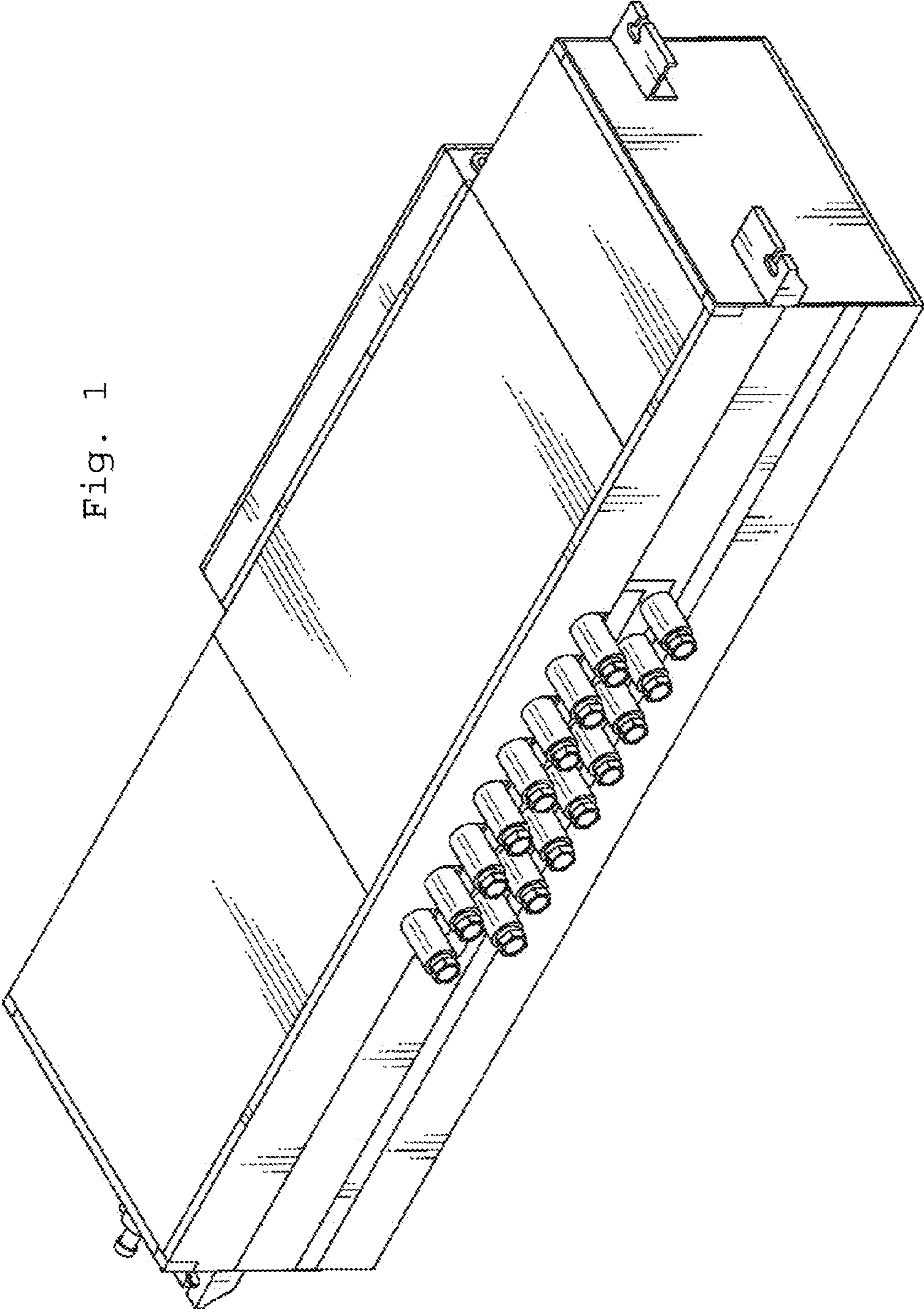


Fig. 2

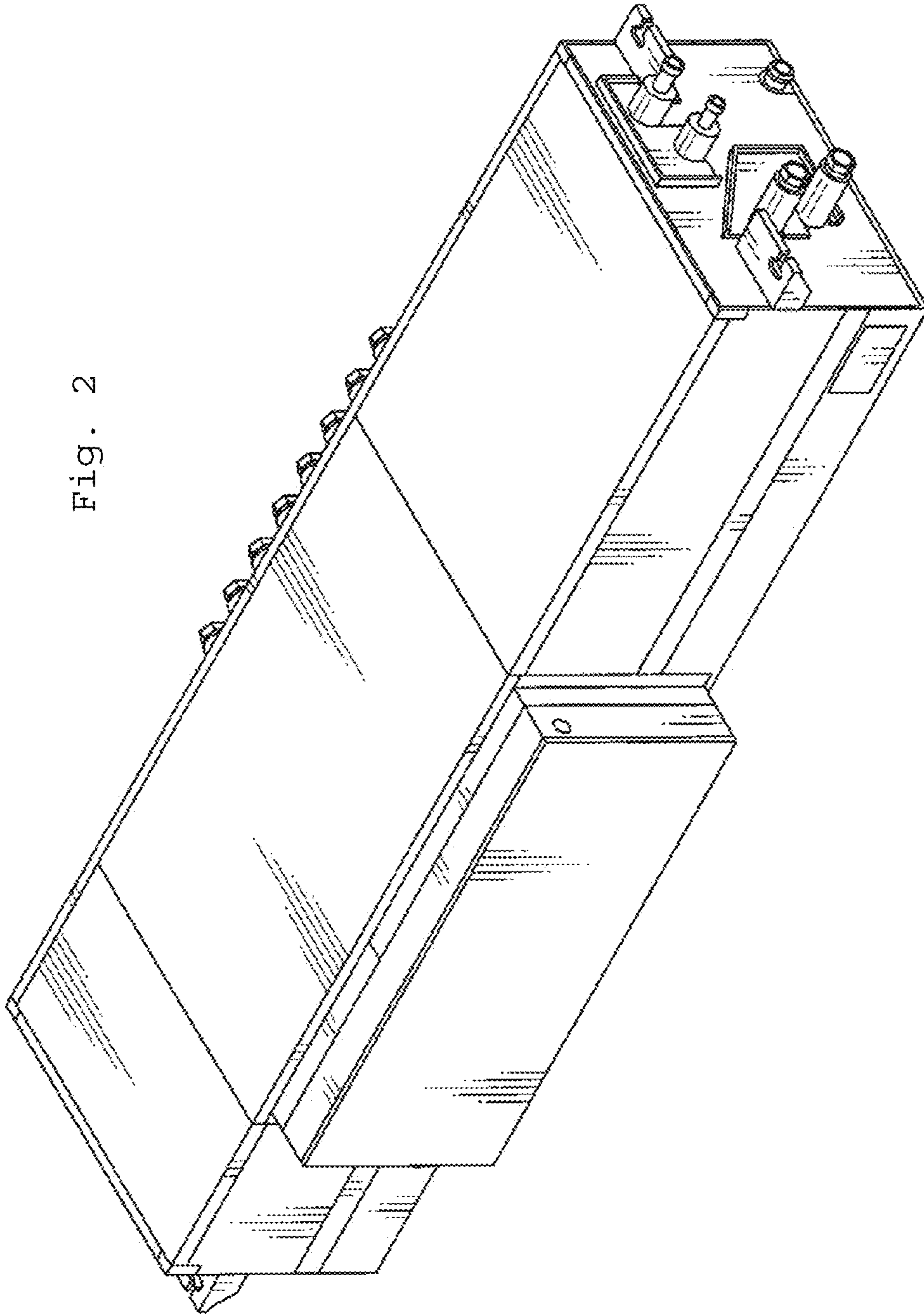


Fig. 3

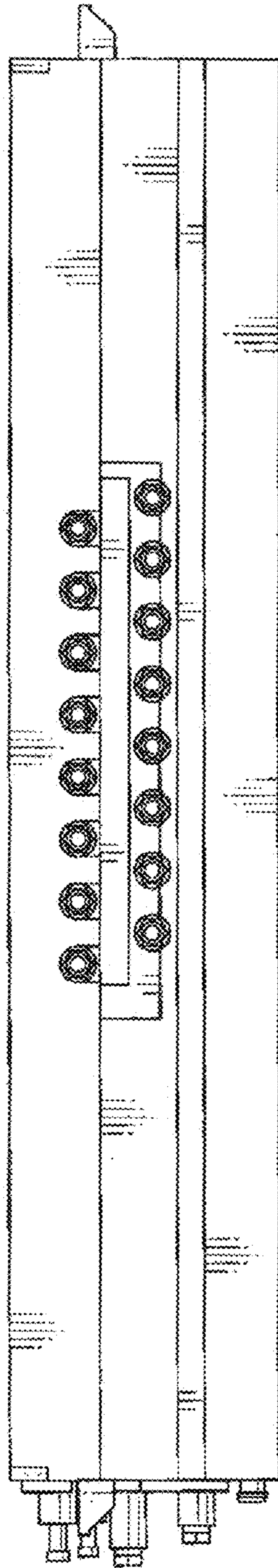


Fig. 4

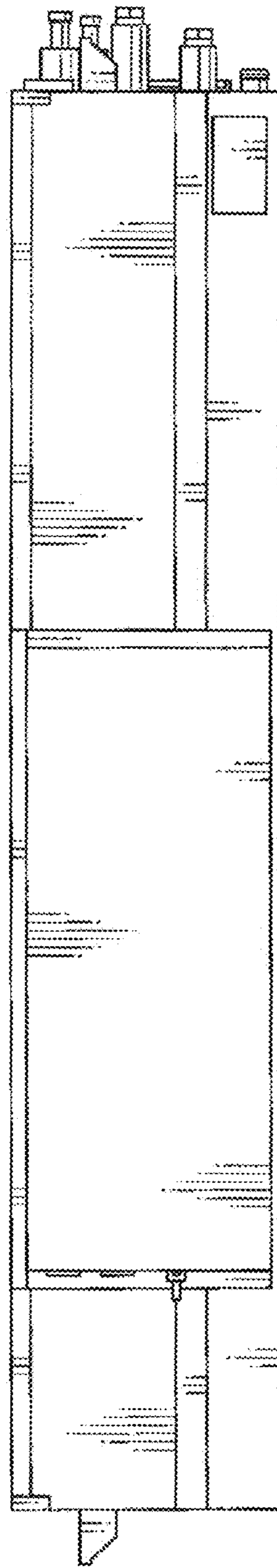


Fig. 6

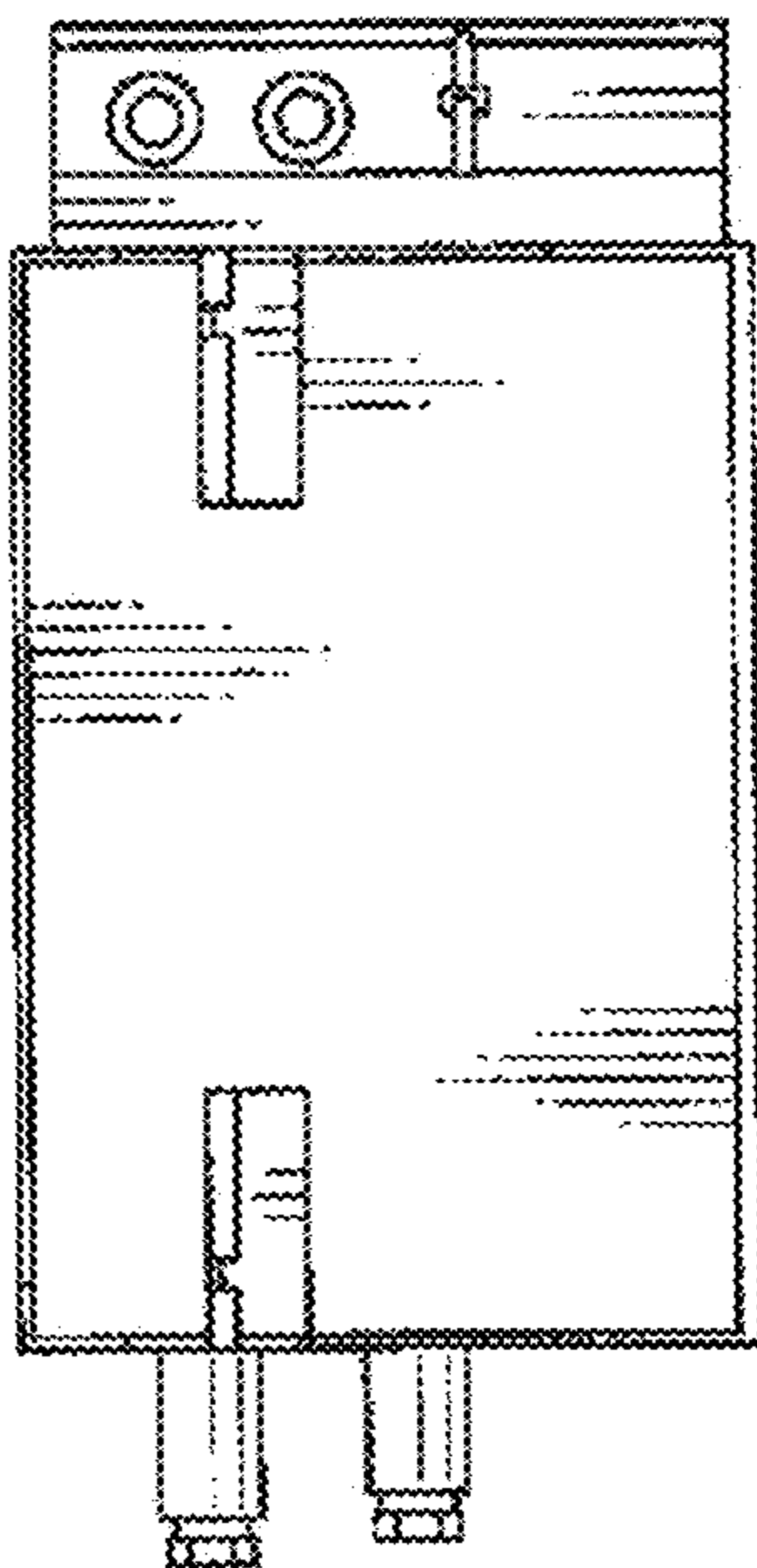


Fig. 5

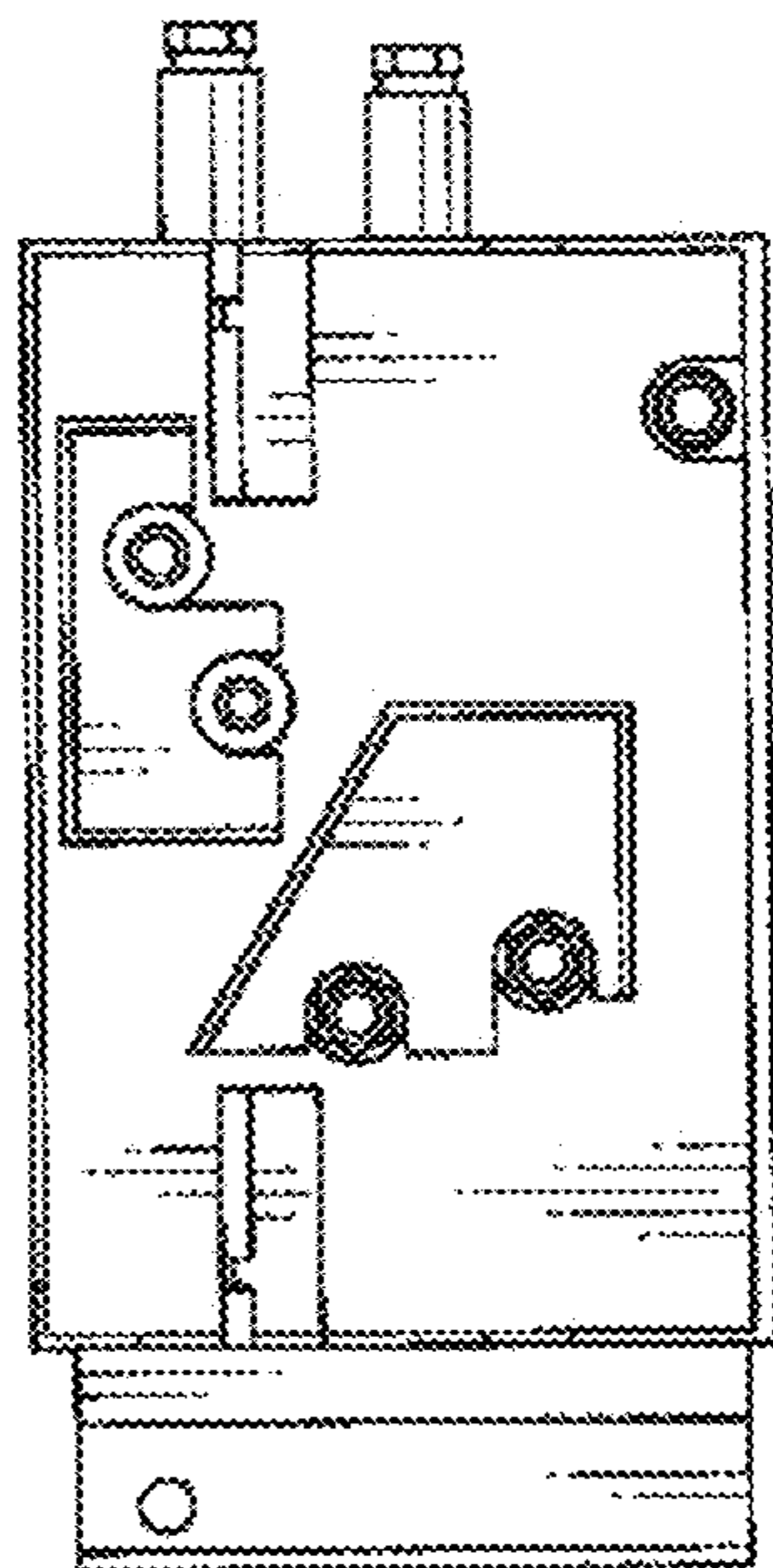


Fig. 7

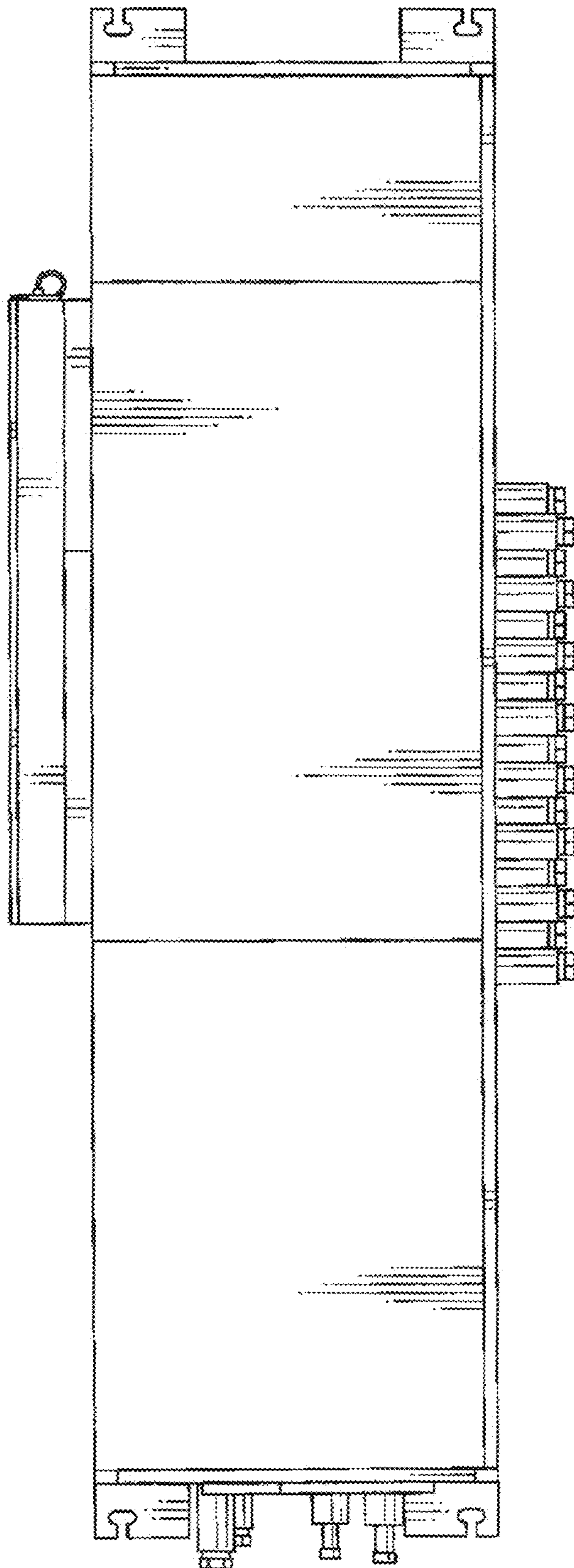


Fig. 8

